

ESCCON 2021
ESTEC 11-13 March 2021

**Feedback on radiation test on SoC Components
which can be very challenging regarding the
complexity of such devices**

Jérôme Carron, David Dangla, Florent Manni, Aurélien Odoude

Introduction

Cartography

CNES activities on COTS SoC

CNES roadmap for COTS SoC

Lessons learned

Conclusion

Introduction

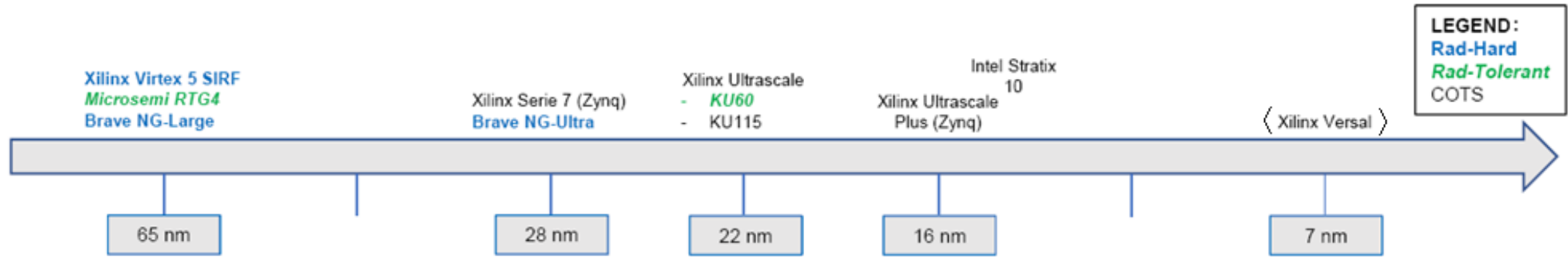
A System on Chip (SoC) is a device who contains various components, such as:

- Processor(s)
- Memories
- Interface/memory drivers
- FPGA
- ...

There are plenty on SoC on the commercial market which is driven by Apple, Intel, Samsung, Nvidia, AMD, Xilinx...

Each manufacturer has his own design specification with an associated market
Most of them are not suitable for space application (in terms of functionalities)
Most of them are not procurable on the commercial market

2 main commercial manufacturers:



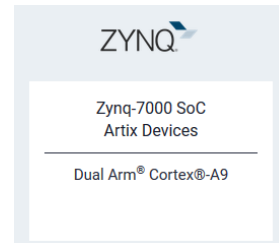
The node size translate the performance in consumption by logic cell.

$$\text{Performance} \approx 1 / \text{node}^2$$

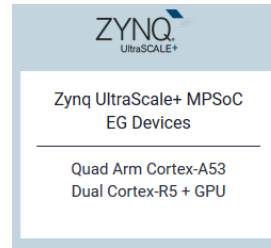
CNES studies :

Chosen on performance and/or on cost basis

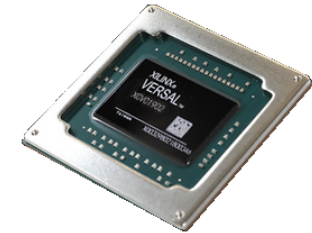
FPGAs



2014



2018



2021

Study on XC7Z030

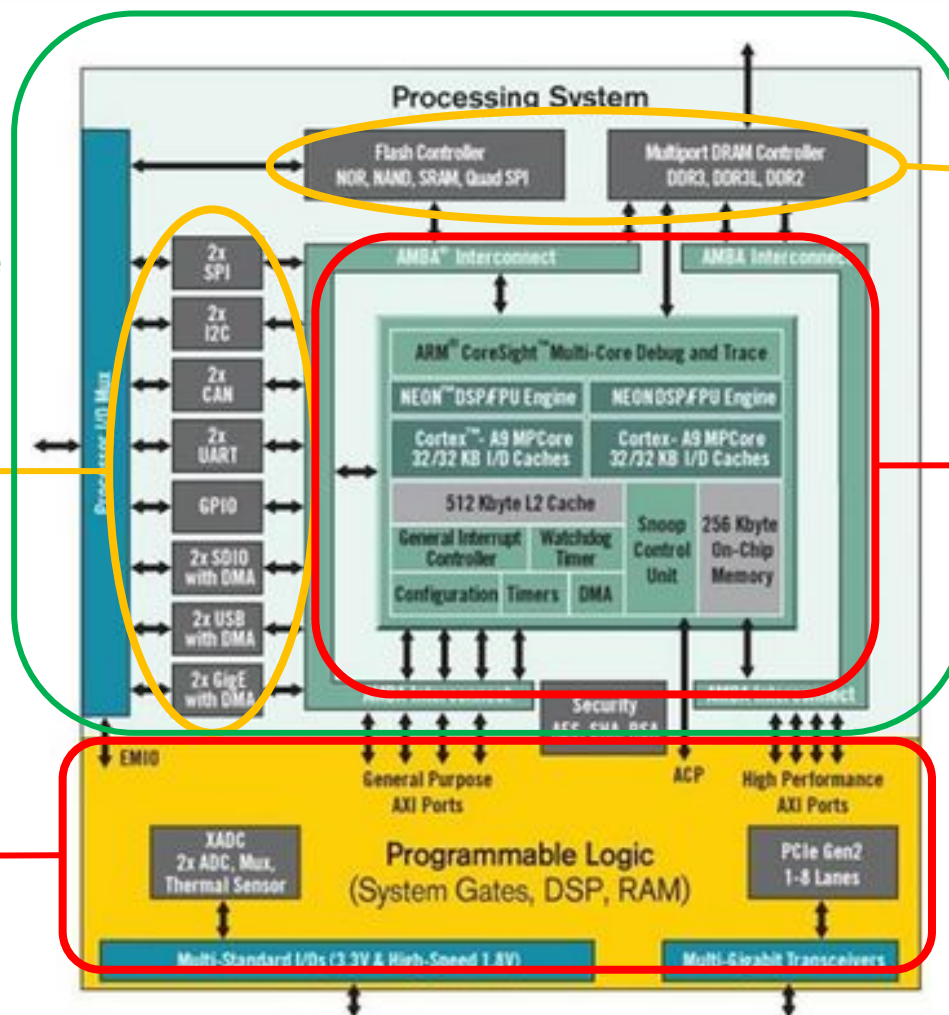
Generic
architecture

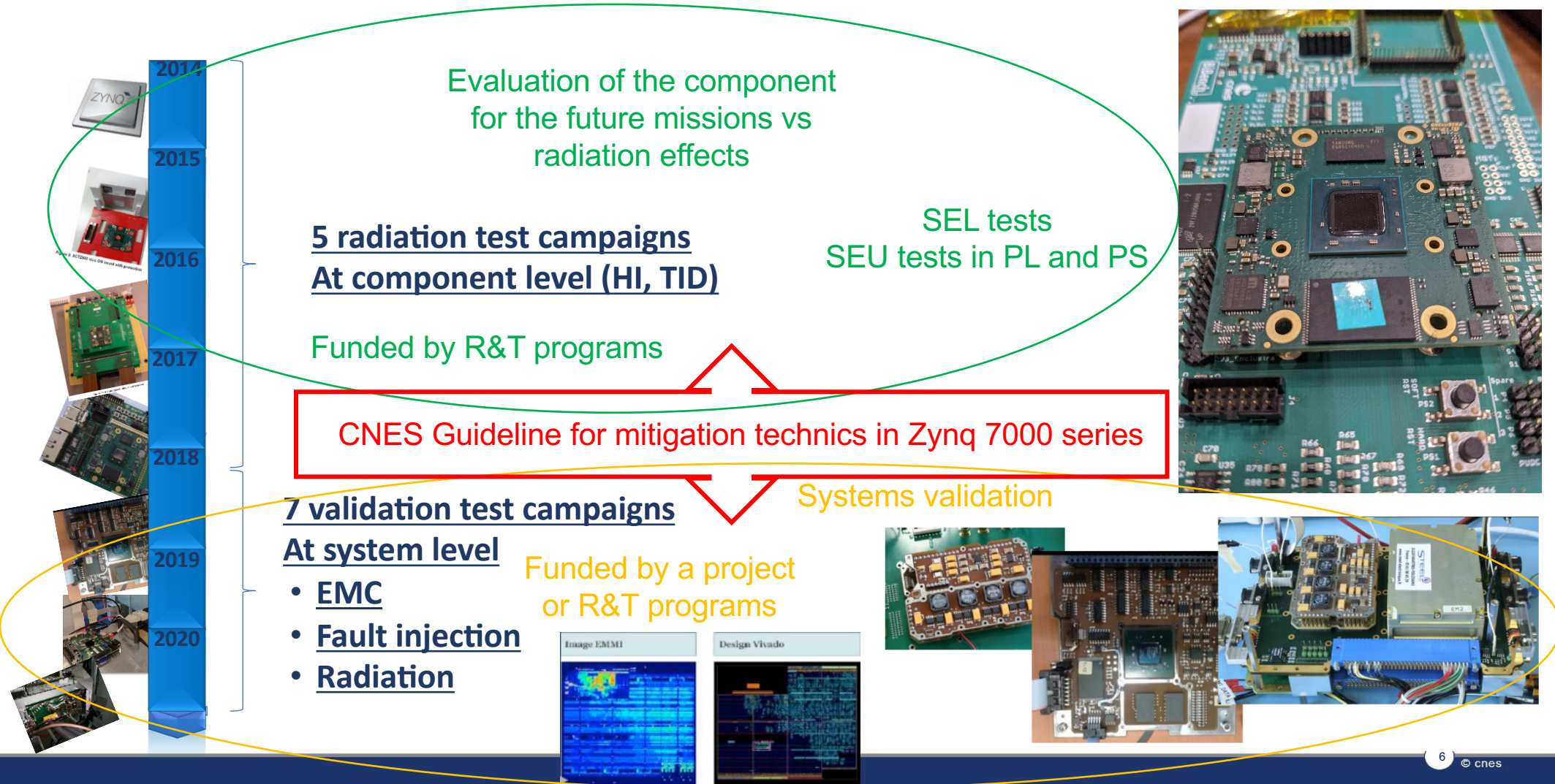
Peripherals

Memory controllers

Dual-Core ARM
Cortex-A9
MPCore Up to 1GHz

FPGA
equivalent to a Kintex-7
125K logic cells



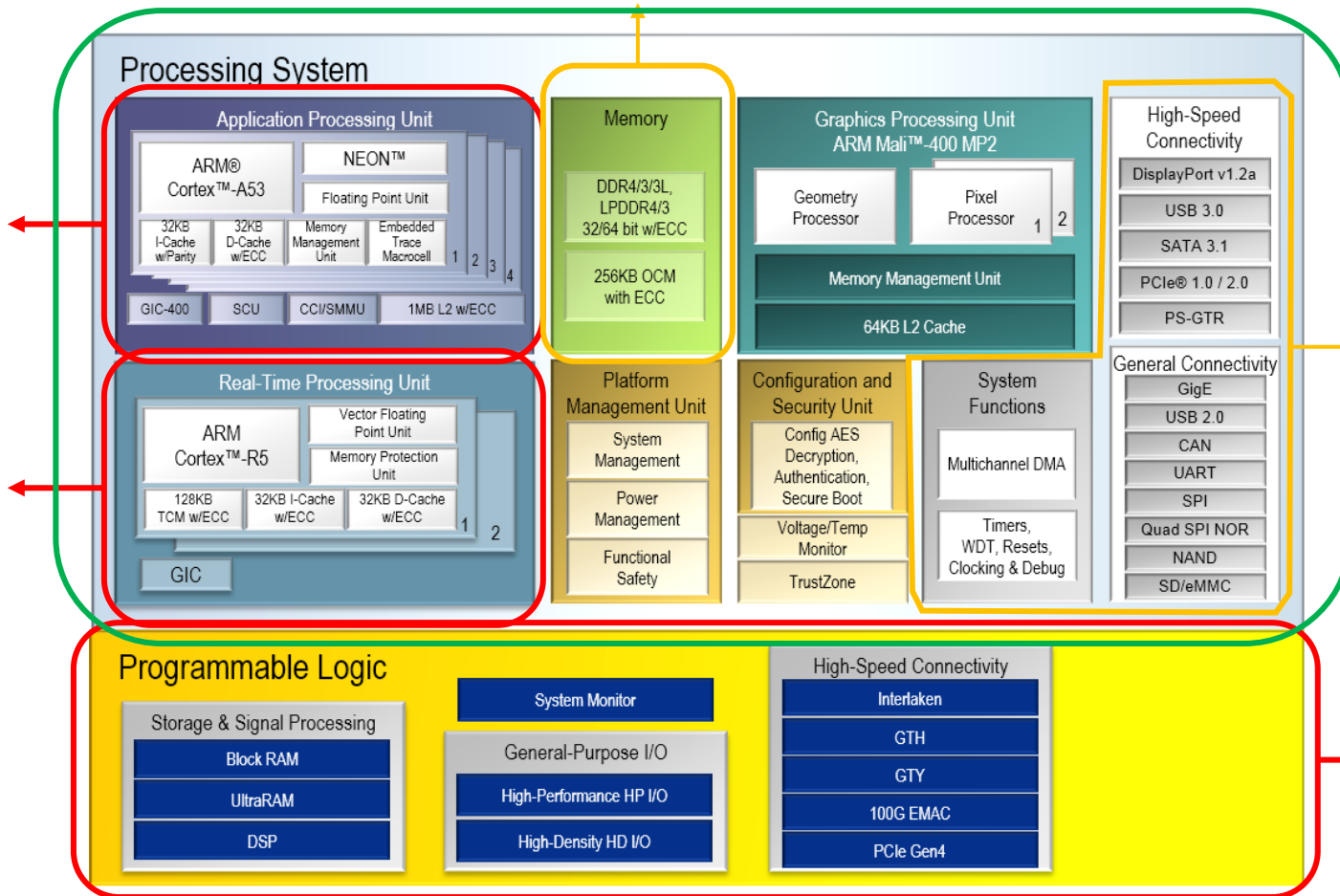


Study on XCZU19EG & XCZU15EG

Memory controllers

Quad-core ARM
Cortex A53
Up to 1.5GHz

Dual-core ARM
Cortex-R5
Up to 600MHz



Peripherals

FPGA
ZU15:
747K logic cells
ZU19:
1143K logic cells

2018

2019

2020

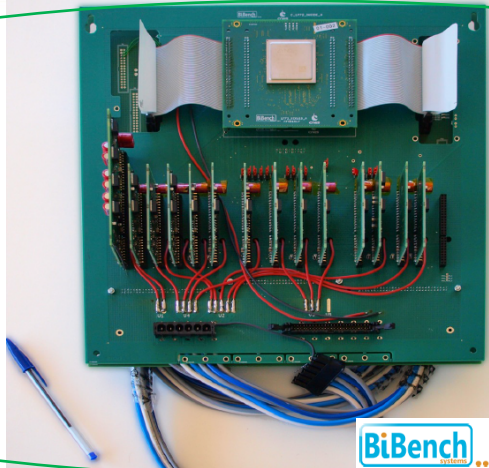
2021

2022

2023

2024

5 radiation test campaigns
At component level
(Jyvaskyla, KVI)



Evaluation of the component
for the future missions vs
radiation effects

Funded by R&T programs

UltraCOM board

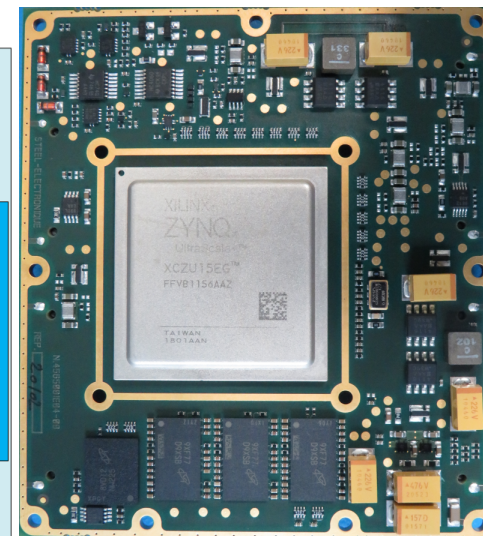
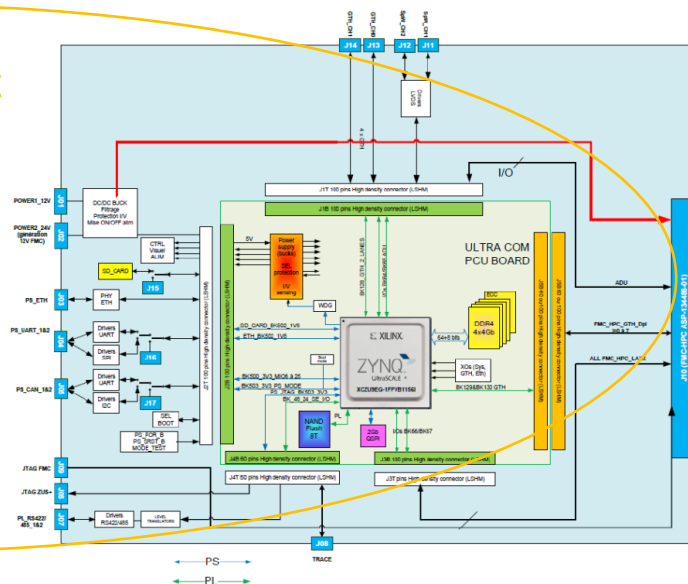
Integrate all needed peripheral ICs
& SEL protections

→ SEL sensitive

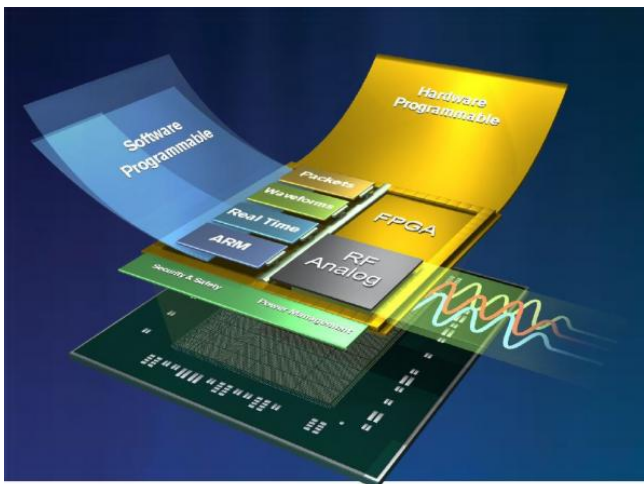
Funded by a project
or R&T programs

XX tests campaigns
At system level

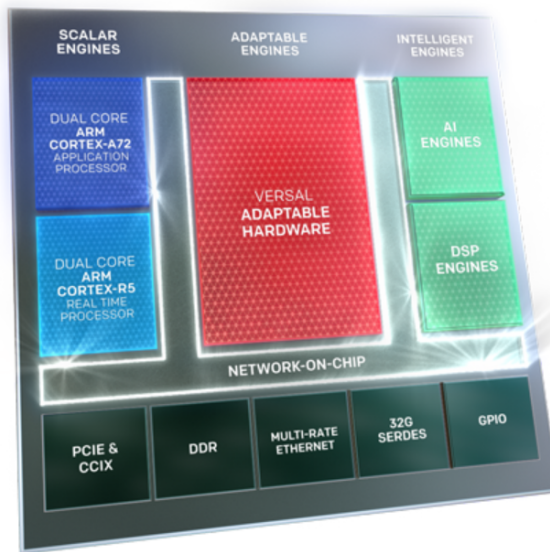
Test of use cases and
mitigation techniques



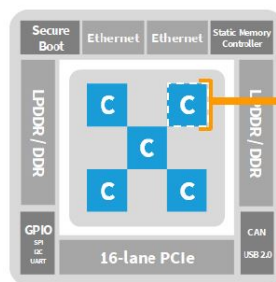
Zynq Ultrascale + RFSoc



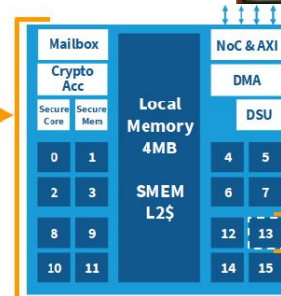
Similar with Zynq Ultrascale +
With additional ADC DAC
for RF processing



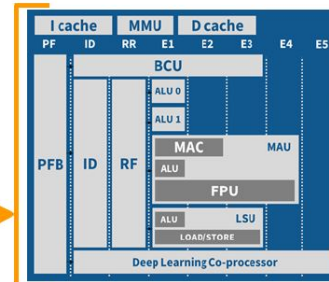
Kalray MPPA Coolidge



MPPA® Manycore
Processor
(5 clusters = 80 cores)



Compute Cluster
(16 cores)



64-bit 3rd Generation
VLIW Core + Accelerators

Future is coming

- **Increase of the capacity and of the numbers of components inside the devices**
- **The architecture are more and more complex at for each new generation**
- **Increase of the data rates and available interfaces**
- **Constant increase of the power supply needs with**
 - **Plenty of power domains**
 - **Various independent power lines**
- **Complexity of the test for SEU and integrated components**
 - **Required a large amount of beam time**
 - **Custom test code needs to be developed**
 - **Access to all the memory blocks are not always feasible**
- **Difficult to clearly understand what's really happen inside the device without support from the manufacturer**
- **Time is needed between each test campaign to really understand what's happened**
- **Ecosystem grows in parallel of the tests/developments**

- **Characterization of SoC is complex and cannot be done on a single radiation test campaign**
- **Tests required skills in various domains**
 - ❖ Hardware
 - ❖ Software
 - ❖ System
 - ❖ Test bench
 - ❖ ...
- **Anticipate as much as possible your next test campaign with preliminary tests**
- **Keep tests simple.**
 - *If the test is too complex it will be difficult to develop the test setup and errors will be difficult to analyze*
- **A global system validation is needed to validate your mitigations technics**
 - A global validation is a project in a project framework
 - A validation with a good coverage is long and complex